

ABSTRACT

SLIDING PROCESS FOR DETACHING A THIN ELECTRONIC DEVICE FROM AN ADHESIVE TAPE

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10 An electronic device to be detached from an adhesive tape is positioned over an abutment protrusion mounted on an ejector assembly along a first axis. The abutment protrusion has a relatively fixed position on the ejector assembly along a second axis that is perpendicular to the first axis. The abutment protrusion first pushes against the electronic device adjacent to a first edge of the electronic device to lift the first edge of the electronic device away from the adhesive tape. The electronic device and the ejector assembly are then slid relative to each other along the second axis while the electronic device is lifted by the abutment protrusion, until the abutment protrusion is pushing against the electronic device adjacent to a second edge of the electronic device opposite to the first edge. An electronic device holder subsequently removes the electronic device from the adhesive tape.

20 (FIG. 1B)